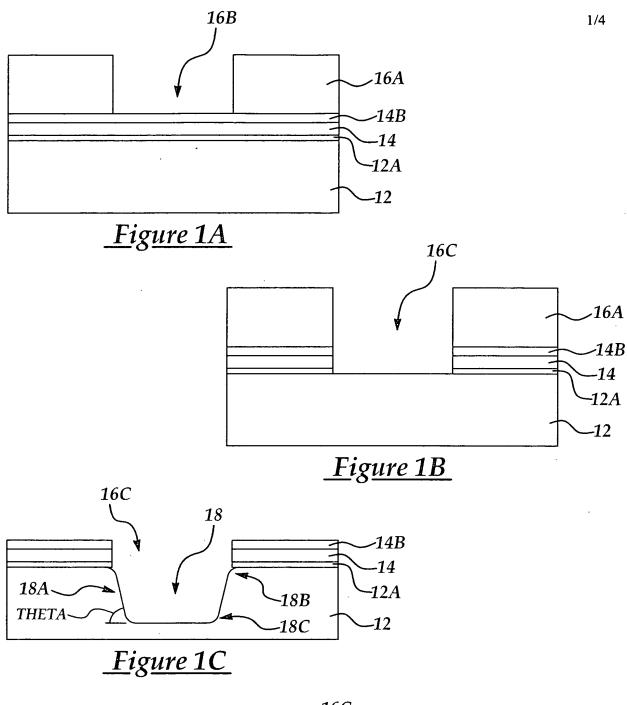
Inventor: Chu-Yun Fu

Serial No.: To Be Assigned Filed: Herewith

For: Methods Of Achieving Improved STI Gap Fill with Reduced Stress

Attorney Doc. No.: 67,200-1189



18A 18B 14B 12A 12A 12A 12C 12

Figure 1D

Inventor: Chu-Yun Fu

Serial No.: To Be Assigned Filed: Herewith

For: Methods Of Achieving Improved STI Gap Fill with Reduced Stress

Attorney Doc. No.: 67,200-1189

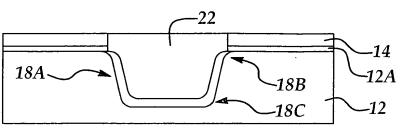
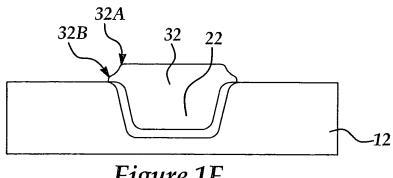


Figure 1E



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Figure 1F

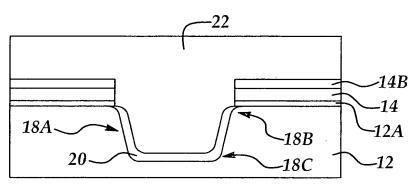


Figure 2A

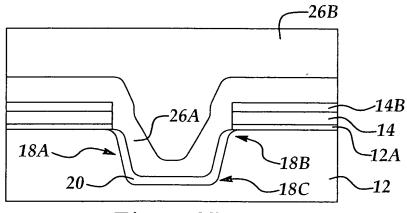


Figure 2B

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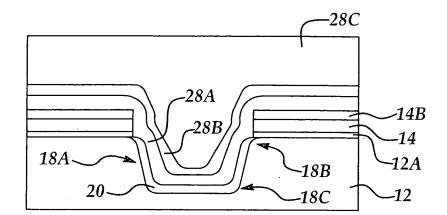


Figure 2C

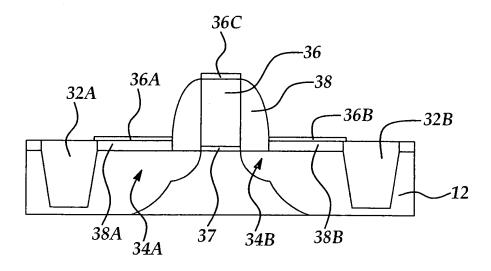
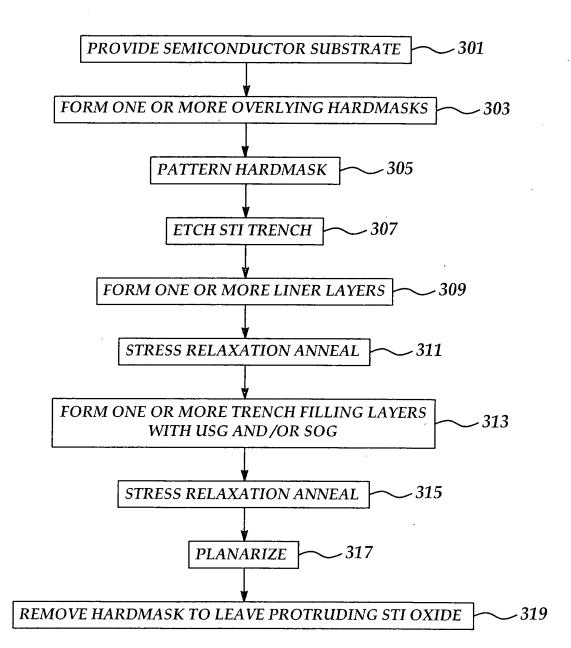


Figure 2D

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<u>Figure 3</u>